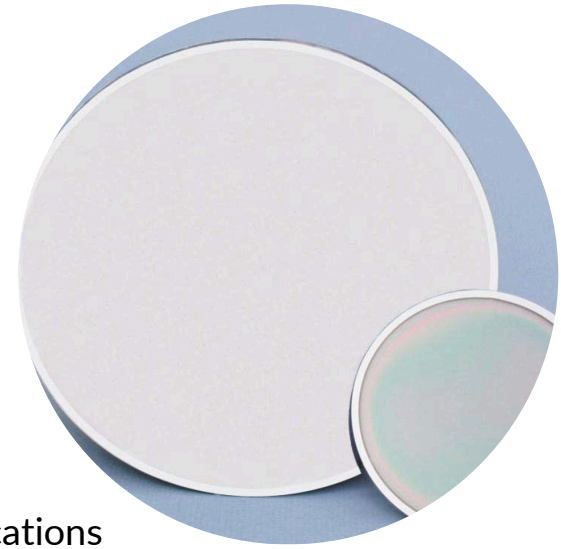
DIAMOND-ON-SILICON WAFERS

Advanced CVD Diamond Coatings,
Wafers and Thermal Technologies

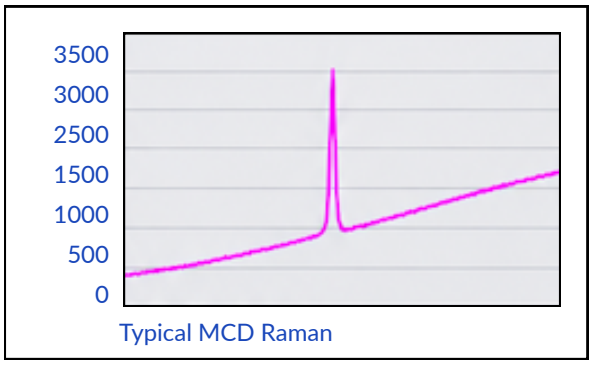


Why sp3

- Exceptional thermal conductivity
- Diamond-on silicon wafer solutions
- Custom coating services
- Scalable production capability and R&D support
- High-performance diamond coatings for advanced applications

Film Types

- Standard diamond films with strong Raman peak
- Smooth films with grain size down to 10 nm
- Undoped and boron-doped conductive films:
  (0.05 to 10 Ohm-cm).



Typical MCD Raman

General Specifications

Wafer diameters:
50, 70, 100, 150, 200, 300 mm

Film thickness:
0.2 µm to 50.0+µm

Wafer flatness typically:
50 µm on 1 µm thickness
for 200 mm wafer

Thickness uniformity:
+/-10%

Grain size down to:
10 nanometers

Youngs modulus:
>1000 GPa

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